

### AMENDMENTS TO THE SPECIFICATION

#### In the Specification:

Please replace the paragraph beginning at page 1, line 16, with the following rewritten paragraph:

Copper and copper base alloy foils are widely used in the printed circuit board industry. The foil is produced to a thickness of under 203 microns (0.008 inch) and more generally to a thickness in the range of from 5.1 microns (0.0002 inch that is known in the art as 1/8 ounce foil) to 1.0 ~~microns~~ micron (0.00004 inch). The foil is typically produced by either mechanical working or electrodeposition. "Wrought" foil is produced by mechanically reducing the thickness of a copper or copper alloy strip by a process such as rolling. "Electrodeposited" foil is produced by electrolytically depositing copper ions on a rotating cathode drum and then peeling the deposited strip from the cathode.